

CTA01 – Geselecteerde uitwerkingen week 1

1.5	processor	clock rate [GHz]	CPI
	P1	3.0	1.5
	P2	2.5	1.0
	P3	4.0	2.2

$$IPS = \frac{\text{clock rate}}{CPI}$$

processor	clock rate [GHz]	CPI	IPS
P1	3.0	1.5	2.00×10^9
P2	2.5	1.0	2.50×10^9
P3	4.0	2.2	1.82×10^9

P2 has the highest performance expressed in IPS.

$$\text{cycles}(10\text{s}) = \text{clock rate} \times 10$$

$$\text{number of instructions}(10\text{s}) = \frac{\text{cycles}(10\text{s})}{CPI} = IPS \times 10$$

processor	clock rate [GHz]	CPI	IPS	cycles	number of instructions
P1	3.0	1.5	2.00×10^9	30×10^9	20.0×10^9
P2	2.5	1.0	2.50×10^9	25×10^9	25.0×10^9
P3	4.0	2.2	1.82×10^9	40×10^9	18.2×10^9

$$\text{execution time} = \frac{\text{number of instructions} \times CPI}{\text{clock rate}}$$

$$\text{old clock rate} = \frac{\text{number of instructions} \times \text{old CPI}}{\text{old execution time}}$$

$$\text{new clock rate} = \frac{\text{number of instructions} \times \text{old CPI} \times 1.2}{\text{old execution time} \times 0.7}$$

$$\text{new clock rate} = \text{old clock rate} \times \frac{1.2}{0.7}$$

processor	old clock rate [GHz]	new clock rate [GHz]
P1	3.0	5.14
P2	2.5	4.29
P3	4.0	6.86

1.10	wafer diameter [cm]	cost	dies/wafer	defects/cm ²
	15	12	84	0.020
	20	15	100	0.031

1.10.1

$$\text{Yield} = \frac{1}{(1 + (\text{Defects per area} \times \text{Die area}/2))^2}$$

$$\text{Die area} = \frac{\text{Wafer area}}{\text{dies/wafer}}$$

$$\text{Wafer area} = \frac{1}{4} \times \pi \times (\text{wafer diameter})^2$$

$$\text{Die area} = \frac{\frac{1}{4} \times \pi \times (\text{wafer diameter})^2}{\text{dies/wafer}}$$

$$\text{Yield} = \frac{1}{\left(1 + \left(\text{Defects per area} \times \left(\frac{\frac{1}{4} \times \pi \times (\text{wafer diameter})^2}{\text{dies/wafer}}\right)/2\right)\right)^2}$$

$$\text{Yield}_{15\text{cm}} = \frac{1}{\left(1 + \left(0.020 \times \left(\frac{\frac{1}{4} \times \pi \times 15^2}{84}\right)/2\right)\right)^2} = 0.9592$$

$$Yield_{20\text{cm}} = \frac{1}{\left(1 + \left(0.031 \times \left(\frac{\frac{1}{4} \times \pi \times 20^2}{100}\right)/2\right)\right)^2} = 0.9093$$

1.10.2

$$\text{cost per die} = \frac{\text{cost per wafer}}{\text{dies/wafer} \times \text{yield}}$$

1.10.3 The number of dies per wafer is increased by 10% ($\times 1.1$). The defects per area increases by 15% ($\times 1.15$).

$$Yield_{15\text{cm}} = \frac{1}{\left(1 + \left(0.020 \times 1.15 \times \left(\frac{\frac{1}{4} \times \pi \times 15^2}{84 \times 1.1}\right)/2\right)\right)^2} = 0.9574$$

$$Yield_{20\text{cm}} = \frac{1}{\left(1 + \left(0.031 \times 1.15 \times \left(\frac{\frac{1}{4} \times \pi \times 20^2}{100 \times 1.1}\right)/2\right)\right)^2} = 0.9055$$